

ABSTRACT OF THE DISCLOSURE

A wiring board for a semiconductor device includes a wiring section disposed on an insulation board and an electromagnetic shielding film disposed at a position close to the wiring section. A distance defined between the wiring section and the electromagnetic shielding film is 50  $\mu\text{m}$  or less and a volume specific resistance of said electromagnetic shielding film is 10  $30 \mu\Omega\cdot\text{cm}$  or less at a room temperature. This structure reduces an inductance of the wiring section and inductive cross talk at frequencies between about 10 MHz to 15GHz.